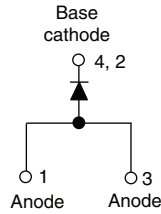


## Schottky Rectifier, 3.0 A



D-PAK (TO-252AA)



### FEATURES

- Popular D-PAK outline
- Small foot print, surface mountable
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Compliant to RoHS Directive 2002/95/EC
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C



PRODUCT SUMMARY	
Package	D-PAK (TO-252AA)
$I_{F(AV)}$	3.0 A
$V_R$	20 V, 30 V, 40 V
$V_F$ at $I_F$	0.49 V
$I_{RM}$	20 mA at 125 °C
$T_J$ max.	150 °C
Diode variation	Single die
$E_{AS}$	8 mJ

### DESCRIPTION

The VS-MBRD320PbF, VS-MBRD330PbF, VS-MBRD340PbF surface mount Schottky rectifier has been designed for applications requiring low forward drop and small foot prints on PC boards. Typical applications are in disk drives, switching power supplies, converters, freewheeling diodes, battery charging, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS			
SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Rectangular waveform	3.0	A
$V_{RRM}$		20 to 40	V
$I_{FSM}$	$t_p = 5 \mu s$ sine	490	A
$V_F$	3 Apk, $T_J = 125 \text{ }^\circ\text{C}$	0.49	V
$T_J$		- 40 to 150	°C

VOLTAGE RATINGS					
PARAMETER	SYMBOL	VS-MBRD320PbF	VS-MBRD330PbF	VS-MBRD340PbF	UNITS
Maximum DC reverse voltage	$V_R$	20	30	40	V
Maximum working peak reverse voltage	$V_{RWM}$				

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	50 % duty cycle at $T_L = 133 \text{ }^\circ\text{C}$ , rectangular waveform		3.0	A
Maximum peak one cycle non-repetitive surge current	$I_{FSM}$	5 $\mu s$ sine or 3 $\mu s$ rect. pulse	Following any rated load condition and with rated $V_{RRM}$ applied	490	
		10 ms sine or 6 ms rect. pulse		75	
Non-repetitive avalanche energy	$E_{AS}$	$T_J = 25 \text{ }^\circ\text{C}$ , $I_{AS} = 1 \text{ A}$ , $L = 16 \text{ mH}$		8.0	mJ
Repetitive avalanche current	$I_{AR}$	Current decaying linearly to zero in 1 $\mu s$ Frequency limited by $T_J$ maximum $V_A = 1.5 \times V_R$ typical		1.0	A

ELECTRICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS		TYP.	MAX.	UNITS
Maximum forward voltage drop See fig. 1	$V_{FM}^{(1)}$	3 A	$T_J = 25\text{ }^\circ\text{C}$	0.48	0.6	V
		6 A		0.58	0.7	
		3 A	$T_J = 125\text{ }^\circ\text{C}$	0.41	0.49	
		6 A		0.55	0.625	
Maximum reverse leakage current See fig. 2	$I_{RM}^{(1)}$	$T_J = 25\text{ }^\circ\text{C}$	$V_R = \text{Rated } V_R$	0.02	0.2	mA
		$T_J = 125\text{ }^\circ\text{C}$		10.7	20	
Typical junction capacitance	$C_T$	$V_R = 5\text{ }V_{DC}$ (test signal range 100 kHz to 1 MHz), $25\text{ }^\circ\text{C}$		189	-	pF
Typical series inductance	$L_S$	Measured lead to lead 5 mm from package body		5.0	-	nH
Maximum voltage rate of change	dV/dt	Rated $V_R$		-	10 000	V/ $\mu$ s

**Note**

(1) Pulse width < 300  $\mu$ s, duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction temperature range	$T_J^{(1)}$		- 40 to 150	$^\circ\text{C}$
Maximum storage temperature range	$T_{Stg}$		- 40 to 175	
Maximum thermal resistance, junction to case	$R_{thJC}$	DC operation See fig. 4	6.0	$^\circ\text{C}/\text{W}$
Maximum thermal resistance, junction to ambient	$R_{thJA}$		80	
Approximate weight			0.3	g
			0.01	oz.
Marking device		Case style D-PAK (similar to TO-252AA)	MBRD320	
			MBRD330	
			MBRD340	

**Note**

(1)  $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{thJA}}$  thermal runaway condition for a diode on its own heatsink

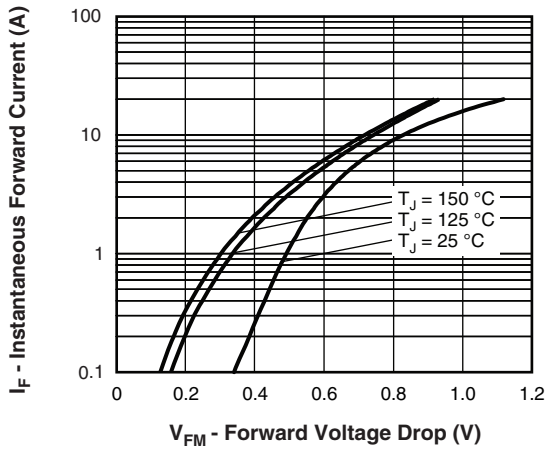


Fig. 1 - Maximum Forward Voltage Drop Characteristics

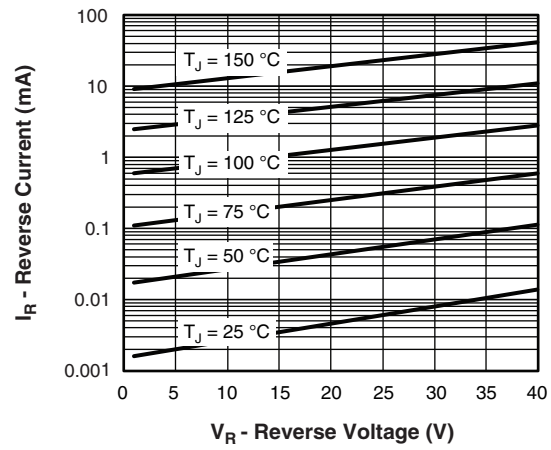


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

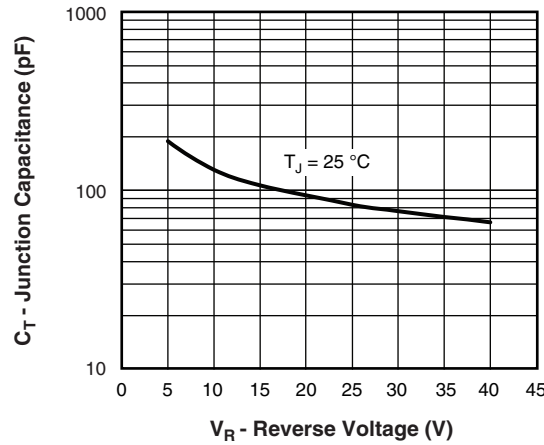


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

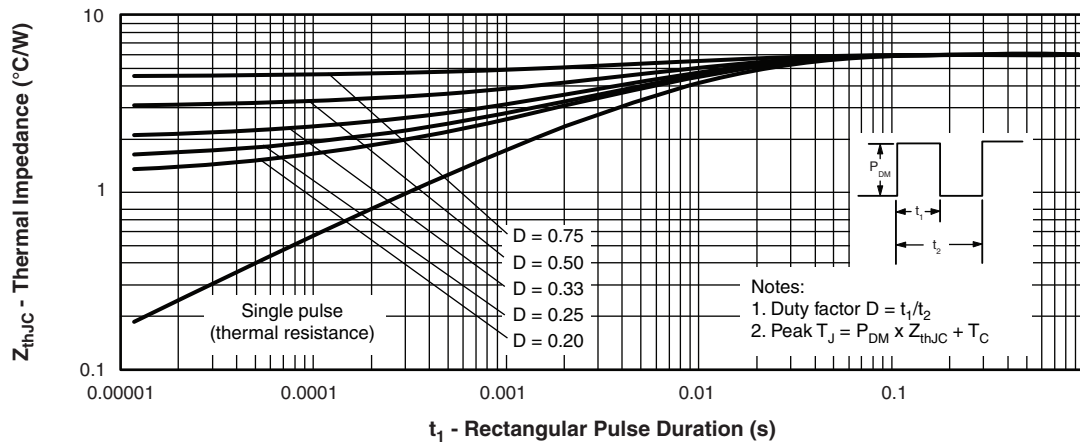


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

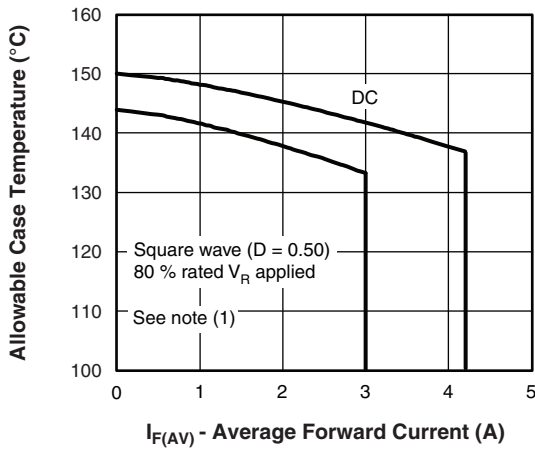


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

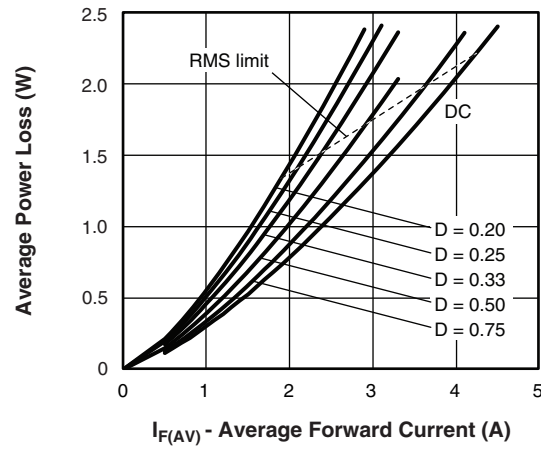


Fig. 6 - Forward Power Loss Characteristics

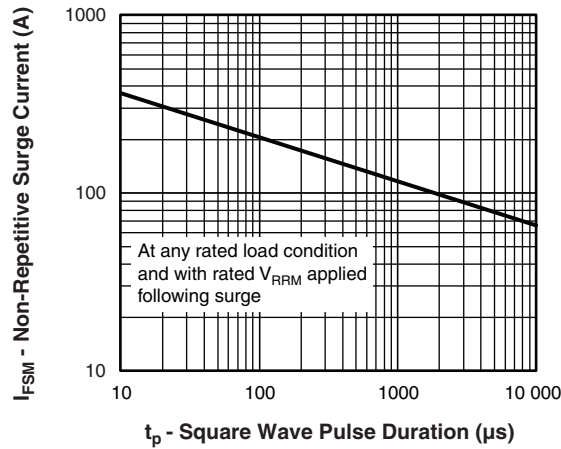


Fig. 7 - Maximum Non-Repetitive Surge Current

**Note**

- (1) Formula used:  $T_C = T_J - (P_d + P_{d_{REV}}) \times R_{thJC}$ ;
- $P_d$  = Forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);
- $P_{d_{REV}}$  = Inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1} = 80\%$  rated  $V_R$

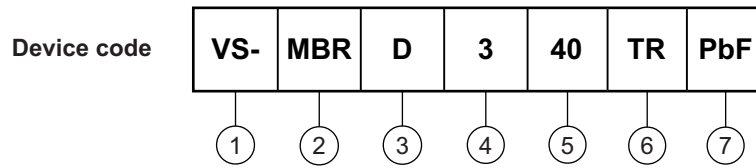


# VS-MBRD320PbF, VS-MBRD330PbF, VS-MBRD340PbF

Schottky Rectifier, 3.0 A

Vishay Semiconductors

## ORDERING INFORMATION TABLE



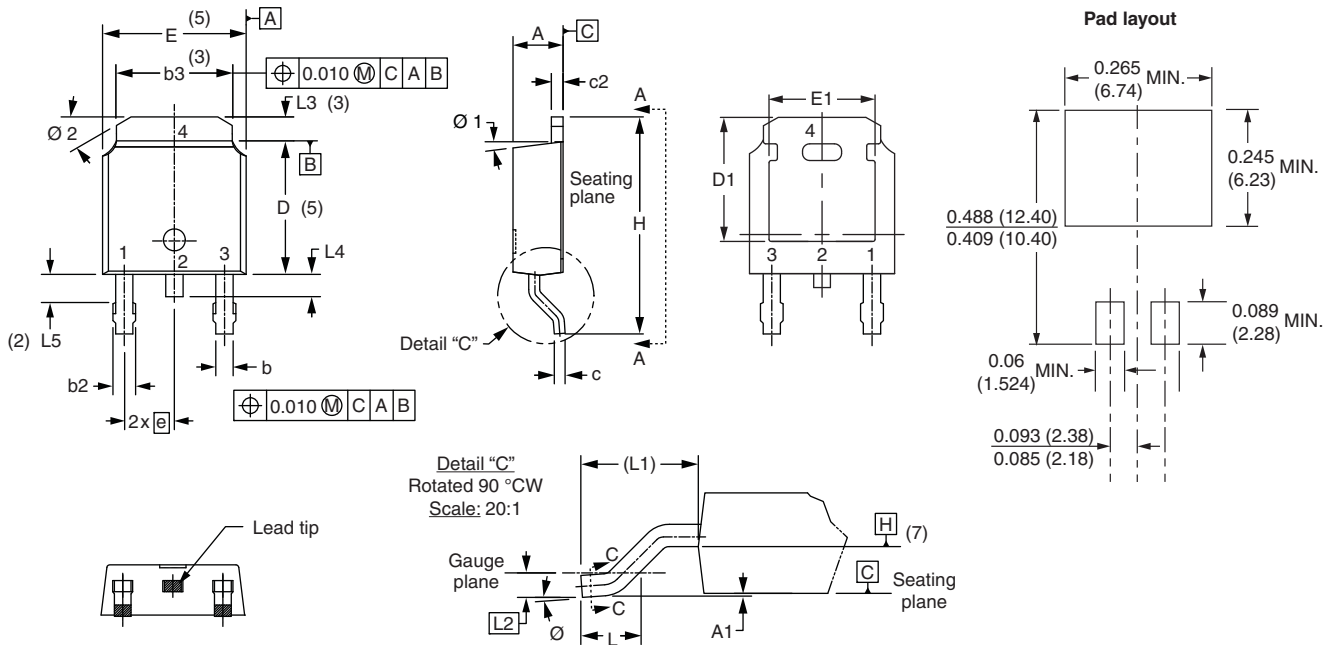
- 1** - Vishay Semiconductors product
- 2** - Schottky MBR series
- 3** - D = TO-252AA (D-PAK)
- 4** - Current rating (3 = 3 A)
- 5** - Voltage ratings
 

20 = 20 V
30 = 30 V
40 = 40 V
- 6** -
  - None = Tube (50 pieces)
  - TR = Tape and reel
  - TRL = Tape and reel (left oriented)
  - TRR = Tape and reel (right oriented)
- 7** - PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95016">www.vishay.com/doc?95016</a>
Part marking information	<a href="http://www.vishay.com/doc?95059">www.vishay.com/doc?95059</a>
Packaging information	<a href="http://www.vishay.com/doc?95033">www.vishay.com/doc?95033</a>

## D-PAK (TO-252AA)

**DIMENSIONS** in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094		e	2.29 BSC		0.090 BSC		
A1	-	0.13	-	0.005		H	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035		L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045		L1	2.74 BSC		0.108 REF.		
b3	4.95	5.46	0.195	0.215	3	L2	0.51 BSC		0.020 BSC		
c	0.46	0.61	0.018	0.024		L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035		L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5	L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3	Ø	0°	10°	0°	10°	
E	6.35	6.73	0.250	0.265	5	Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3	Ø2	25°	35°	25°	35°	

**Notes**

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC outline TO-252AA



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